

ON Semiconductor				10/15/2019	
Base Part		FAN73892	HF	Pb-free	
Orderable Part		FAN73892MX	Total weight (mg)	783.9898	
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight	
Die	37.789	Silicon (Si)	7440-21-3	100	
Die Attach	0.6272	Silver (Ag)	7440-22-4	40.5	
		Phenolic Resin-2	54208-63-8	59.5	
Lead Frame	250.872	Silver (Ag)	7440-22-4	0.59711726	
		Zinc (Zn)	7440-66-6	0.14987723	
		Iron (Fe)	7439-89-6	2.09987563	
		Copper (Cu)	7440-50-8	97.00325265	
		Phosphorus (P)	7723-14-0	0.14987723	
Mold Compound-Black	470.4	Ortho Cresol Novolac Resin	29690-82-2	8	
		Carbon Black (C)	1333-86-4	0.29995748	
		Fused Silica (SiO2)	60676-86-0	85.70004252	
		Phenolic Resin (Novolac)	9003-35-4	6	
Plating	23.5176	Tin (Sn)	7440-31-5	100	
Wire Bond - Au	0.784	Gold (Au)	7440-57-5	100	
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>					